

# Q-Pad® II

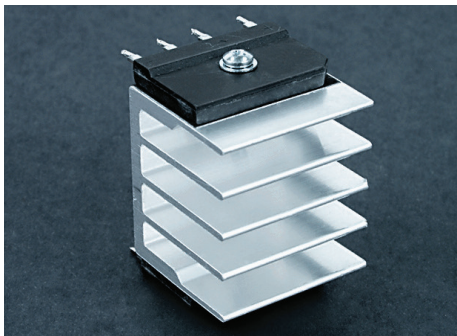
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## PRODUCT DESCRIPTION

Foil-Format Grease Replacement for Maximum Heat Transfer

## FEATURES AND BENEFITS

- Thermal impedance: 0.22°C-in<sup>2</sup>/W (@50 psi)
- Maximum heat transfer
- Aluminum foil coated both sides
- Designed to replace thermal grease



Q-Pad® II is a composite of aluminum foil coated on both sides with thermally/ electrically conductive Sil-Pad® rubber. The material is designed for those applications in which maximum heat transfer is needed and electrical isolation is not required. Q-Pad® II is the ideal thermal interface material to replace messy thermal grease compounds.

Q-Pad® II eliminates problems associated with grease such as contamination of reflow solder or cleaning operations. Unlike grease, Q-Pad® II can be used prior to these operations. Q-Pad® II also eliminates dust collection which can cause possible surface shorting or heat buildup..

*Note: To build a part number, visit our website at [www.bergquistcompany.com](http://www.bergquistcompany.com).*

## TYPICAL PROPERTIES OF Q-PAD II

PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	Black	Black	Visual			
Reinforcement Carrier	Aluminum	Aluminum	—			
Thickness (inch) / (mm)	0.006	0.152	ASTM D374			
Hardness (Shore A)	93	93	ASTM D2240			
Continuous Use Temp (°F) / (°C)	-76 to 356	-60 to 180	—			
<b>ELECTRICAL</b>						
Dielectric Breakdown Voltage (Vac)	Non-Insulating	Non-Insulating	ASTM D149			
Dielectric Constant (1000 Hz)	NA	NA	ASTM D150			
Volume Resistivity (Ohm-meter)	10 <sup>2</sup>	10 <sup>2</sup>	ASTM D257			
Flame Rating	V-O	V-O	U.L.94			
<b>THERMAL</b>						
Thermal Conductivity (W/m-K)	2.5	2.5	ASTM D5470			
<b>THERMAL PERFORMANCE vs PRESSURE</b>						
	Pressure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W)		2.44	1.73	1.23	1.05	0.92
Thermal Impedance (°C-in <sup>2</sup> /W) (1)		0.52	0.30	0.22	0.15	0.12
1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.						

## TYPICAL APPLICATIONS INCLUDE

- Between a transistor and a heat sink
- Between two large surfaces such as an L-bracket and the chassis of an assembly
- Between a heat sink and a chassis
- Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

## CONFIGURATIONS AVAILABLE

- Sheet form, die-cut parts and roll form
- With or without pressure sensitive adhesive

## Disclaimer

### Note:

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